



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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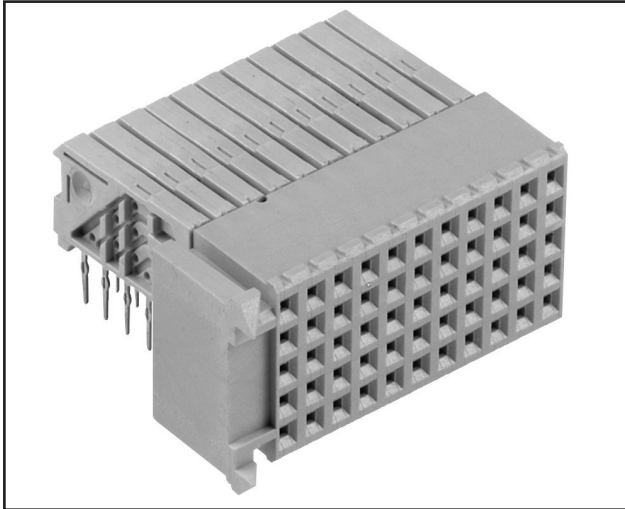
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



3M™ MetPak™ HM Press-Fit Socket

2 mm Type B25, 125 Signal Contacts, 5 Rows, Right Angle

HM Series



- Modular/scalable format IEC 61076-4-101
- 63 mated lines per linear inch
- Dual beam contact construction for high reliability
- End-to-end stackable with 5 row 3M™ MetPak™ CP2, HM and HSHM Products
- Mates with 3M™ MetPak™ HSHM headers
- See the Regulatory Information Appendix (RIA) in the “RoHS compliance” section of www.3mconnector.com for compliance information

Date Modified: November 22, 2010

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Physical

Insulation:

Material: High Temperature Thermoplastic (LCP)
Flammability: UL 94V-0

Color:

Material: Copper Alloy
Plating: See Ordering information

Marking: 3M Logo, Part Number, Revision, Date Code

Performance

Mechanical:

Normal Force (Nominal): 0.57 N [58 g] Signal
Engagement Force (Nominal): 0.32 N [33 g] Signal
Separation Force (Nominal): 0.20 N [20 g] Signal
Wipe (Nominal, Shortest Contact): 2.67 mm [0.105 in] Signal
Mate/Unmate Cycles: 250
Application: This module is not suitable for stand-alone use. (Refer to IEC-61076-4-101)

Electrical:

Current Rating (Fully Loaded): 1 A @ 70° C Signal
Insulation Resistance: $1 \times 10^4 \text{ M}\Omega$ @ 100 V_{DC}
Withstanding Voltage: 750 V_{rms}

Environmental

Temperature Rating: -55° C to 125° C

UL File No.: E68080

MetPak is a trademark of 3M Company.

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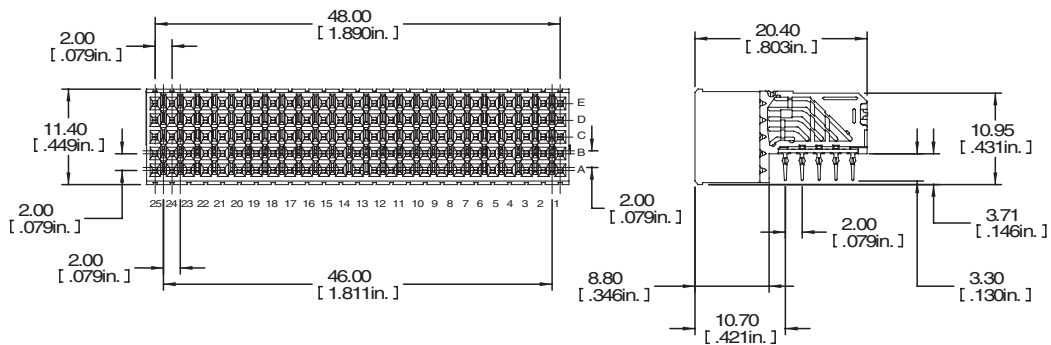
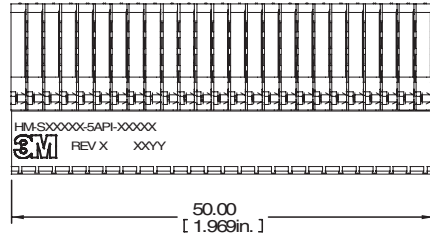
HM Series



mm
(Inch)

Tolerance Unless Noted			
	0	0.0	0.00
mm	±3	±0.3	±0.13

[] Dimensions for Reference Only



Ordering Information

HM-S125B1 - 5AP1 - XXXXX

Plating μm [μin]:

TG30 = 0.76 [30] Min. Au Contact Area
 2.54 [100] Min. SnPb Terminal Area (RIA C2 & E2 apply)
 1.27 [50] Min. Ni All over
 Standard Option

TG30L = 0.76 [30] Min. Au Contact Area, Lubricated
 2.54 [100] Min. SnPb Terminal Area (RIA C2 & E2 apply)
 1.27 [50] Min. Ni All over
 Typically higher make order quantities as compared to TG30.

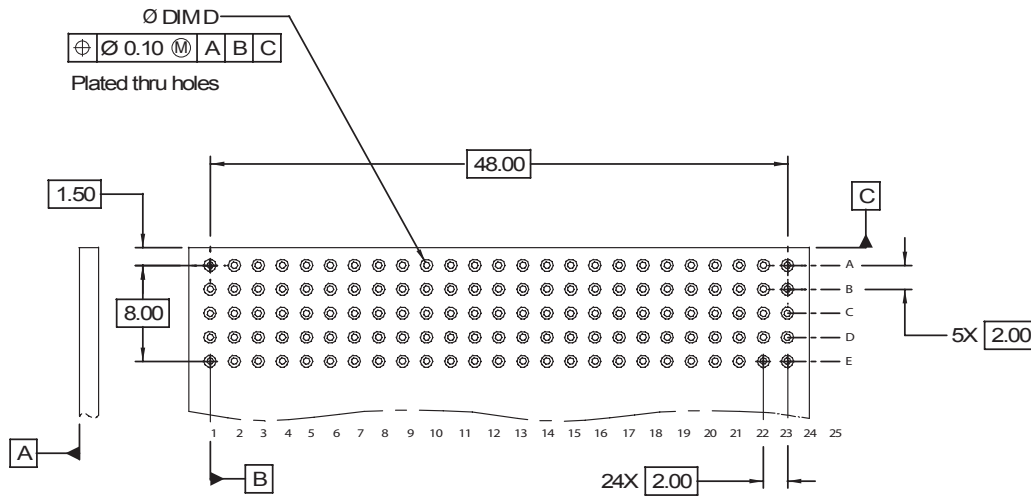
TG50 = 1.27 [50] Min. Au Contact Area, Lubricated
 2.54 [100] Min. SnPb Terminal Area (RIA C2 & E2 apply)
 1.27 [50] Min. Ni All over
 Non-Standard Option (Available with longer lead times and higher make order quantities, MOQ)

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HM Series



Recommended PCB hole mounting pattern

Hole Plating Table

Finished Hole Dia. "D"	Cu. Thickness	SnPb Thickness	Drilled Hole Dia.
0.550-0.650 [.0217-.0256]	0.025-0.045 [.0010-.0018]	0.008-0.018 [.0003-.0007]	0.686-0.727 [.0270-.0286]

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